



High frequency operation
High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
Guard ring for enhanced ruggedness and long term reliability
Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

: TO-220AC

Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant

: Tin plated leads, solderable per J-STD-002 and JESD22-B102

: As marked

($T_a=25$ Unless otherwise specified)

Device marking code			MBR10300
Repetitive Peak Reverse Voltage	VRRM	V	300
Average Rectified Output Current @60Hz sine wave, R-load, $T_a=25$	IO	A	10
Surge(Non-repetitive)Forward Current @60Hz half sine-wave, 1 cycle, $T_a=25$	IFSM	A	200
Current Squared Time @1ms $t<8.3ms$ $T_j=25$	I^2t	A^2s	167
Storage Temperature	T_{stg}		-55 ~ +150



$T_a=25$ Unless otherwise specified

Thermal Resistance	Between junction and case	R J-C	W	2.0

(Example)

MBR10300

Approximate 1.8



